PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V
1.2 PCN No.		MDG/20/12156
1.3 Title of PCN		New dicing tape for saw wafers at Chipbond
1.4 Product Category		Memory products and Secure MCU in sawn wafer delivery form at Chipbond (Taiwan).
1.5 Issue date		2020-06-08

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Rita PAVANO

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	(Not Defined)	Chipbond subcontractor (Taiwan)

4. Description of change		
	Old	New
4.1 Description	The UV curable dicing tape for products in sawn wafer delivery form is Lintec ADWILL D185.	The UV curable dicing tape for products in sawn wafer delivery form will changed to Lintec D176D.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	The dicing tapes can be recognized thanks to their different colors: - D185 dicing tape is opaque - New D176D dicing tape is blue	

5. Reason / motivation for change	
	The new Lintec tape D176D is DEHP free and is introduced to comply with RoHS and REACH environmental requirements.
5.2 Customer Benefit	ENVIRONMENT FOOTPRINT

6. Marking of parts / traceability of change		
6.1 Description	N/A	

7. Timing / schedule	
7.1 Date of qualification results	2020-06-05
7.2 Intended start of delivery	2020-09-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation		
	In progress	

9. Attachments (additional documentations)

12156 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ST25TV64K-AP6G3	

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Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : New dicing tape for saw wafers at Chipbond PCN Reference : MDG/20/12156

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

ST25TB512-AC6G6	ST25TV512-AP6F3	ST25TV512-AD6G9
ST25TA02KB-AC6F5	ST25TV02K-AP6F3	ST25TV64K-AP6G3
ST25TA02KB-AC6G5	ST25TV02K-AP6F9	ST25TV02K-AP6G3
ST25TA16K-AB6G3	ST25TB02K-AC6G6	ST25TV16K-AP6G3
ST25TA64K-AB6G3	ST25TV512-AP6F9	ST25TB512-AT6G6
ST25TV02K-AD6G3	ST25TV512-AD6G3	ST25TV512-AP6G9
ST25TB512-AT6F6	ST25TB04K-AC6G6	ST25TA512B-AC6G5
M24SR04-GSG12I/2	ST25TA512B-AC6F5	ST25TV04K-PE6G3
ST25TV512-AP6G3	ST25TA02K-AC6F5	ST25TA512-AC6G5
ST25TA02K-AC6G5	ST25TA512-AC6F5	ST25TA02K-PC6G5

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